

Damage Tolerance and Durability of Adhesively Bonded Composite Structures

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JMS Damage Tolerance and Durability of Adhesively Bonded Composite Structures

Motivation and Key Issues

- failure prediction of composite adhesive joints remains a difficult problem
 - multiple failure modes and complex failure processes
 - damage initiation and growth influenced by geometry, loading, and environmental factors such as moisture, temperature, etc.
- damage in joints is difficult to detect must design structures to be tolerant to reasonably-sized flaws
 - accurate models are needed to predict failure and assess damage tolerance
- Objectives
 - investigate physical phenomena and processes leading to failure in adhesively bonded joints
 - account for bondline thickness and environmental conditions
 - develop models describing these phenomena
- Approach: combined experimental/analytical investigations supporting development of models



- Principle Investigators & Researchers
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- FAA Technical Monitor
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- Adhesive constitutive behavior for use in bonded joint analyses
- Effect of adhesive thickness on mixed mode fracture of joints
- Effect of bondline thickness on strength of adhesively bonded joints – CTOA approach
- Influence of moisture and bondline thickness on joint fracture



Adhesive Constitutive Behavior in Bonded Joints

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Background

- nonlinear adhesive constitutive behavior is needed to conduct modeling/analysis e.g., FEA
 - choice of constitutive curve is not clear
- adhesive τ vs γ measured by ASTM D5656:
 - exhibits bond thickness dependency
 - criticized as being inconsistent at ASTM Symposium on Joining and Repair of Composites (March 2003), and at FAA Adhesive Joints Workshop (June 2004)
- <u>material property</u> should be geometry independent

Objectives:

- understand why ASTM D5656 behavior is bondline-thickness dependent
- establish more direct and simple test method for determining constitutive behavior: tensile dogbone, t.b.d. method
- resolve differences observed between tensile dogbone test & ASTM D5656



Shear Stress vs. Shear Strain Relationship for PTM&W ES6292 Measured by ASTM D5656 Test Method





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Cytec FM 73 film adhesive

PTM&W ES6292 epoxy paste adhesive





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0.5 ty/ dt 0.4

Discussion

0.8

- localized damage evolution:
 - highly constrained bondline permits localized failure prior to joint final failure
 - increased compliance effectively _ showing plastic "plateau" and large final failure strain in D5656 tests run under displacement control
 - FEA models must capture this phenomenon



strain rate dependency:

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- adhesive exhibits strain rate dependency
- strain rate in joint ~ 10^{-1} s⁻¹ _
- strain rate in bulk tensile coupon less _ than $\sim 10^{-3} \, {\rm s}^{-1}$
- must model adhesive using viscoplastic material (Zgoul M. and Crocombe 2004)



t, = 0.02 in.





- D5656 thick adherend data measured for PTM&W ES 6292 adhesive
 - show strong bondline thickness dependency
- bulk tensile coupons tested to measure adhesive constitutive behavior directly
- FEA models of D5656 specimens using bulk-measured tensile data predicts only initial portion of specimen behavior
- issues exist:
 - premature failure of bulk tensile specimens not measuring entire constitutive behavior
 - improved test is needed
 - to replicate D5656 data using bulk tensile coupon data, FEA modeling must account for
 - strain rate dependency
 - localized damage evolution



Effect of Adhesive Thickness on Mixed Mode Fracture of Joints

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Background and Objectives



Background

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- fracture mechanics is capable tool for damage tolerance analysis
- need mixed mode strain energy release rate (SERR) data

Objectives

- measure mixed mode SERR for range of bondline thickness
 - Mixed Mode Bending (MMB), DCB, ENF
- observe processes occurring at crack tip
- use modeling/analysis to understand bondline effect in measured data – establish fracture criteria in joints that accounts for bondline thickness dependent G_{IC} and G_{IIC}









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- failure modes
 - all specimens exhibited cohesive failure
 - data omitted if any amount of adhesion (clean interface) failure observed
 - stable crack growth leaves behind rough fracture surface
- pure mode II: 20 and 60 mil bondline specimens exhibited bimodal behavior
 - stable growth rough fracture surface; $G_{IIC} \sim 10 22$ lb/in
 - unstable growth smooth fracture surface ; $G_{IIC} \sim 2.5$ lb/in







- significant plastic strain developed ahead of crack tip prior to growth
- confinement of plastic zone by adherends known to play key role in fracture



Pure Mode II Loading Bondline Thickness: 0.060 in.

CECAN

Microscope Field of View:



Crack Tip

Growth Initiation



- G_C measured as function of mode mixity (modes I and II), and bondline thickness
- 8 mil bondline exhibits monotonically increasing G_C for higher mode II content
- 20 and 60 mil bondlines exhibit bimodal behavior for 100% mode II
 - stable growth / rough fracture surface high G_{IIC}
 - unstable growth / smooth fracture surface -low G_{IIC}
- large plastic deformation observed to develop ahead of crack tip
- FEA modeling of fracture tests is under-way to quantify plastic zone size and confinement/interaction with adherends
 - validation to be achieved via comparison with image-analysis measurements of shear strain



Effect of Bondline Thickness on Strength of Adhesively Bonded Joints

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- To understand the mechanism that effects the thickness-dependent joint strength behavior in adhesively bonded joints
- To develop a CTOA approach for predicting crack growth in bonded joints with the capability of accounting for the effect of bondline thickness





Adherend: Aluminum Alloy 7075

Adhesive: PTM&W ES6292

Surface Treatment: Semco Pasa-Jell 105 (etching method)





The joint strength decreases as the adhesive thickness increases



Total length of the specimen: 4 in

Pre-crack length: 1.5 in

Adherend: Aluminum 7075

Adherend thickness: 125mil (0.125 in)

Adhesive: Hysol EA9394 Thickness range: 27mil-120mil



CTOA Measuring with Crack Propagation







Initial State



Before crack initiation

0.2 mm



Crack Propagation





JMS Effect of Bondline Thickess on DCB Fracture Load



Load and Displacement at the Opening End of the Specimens









Plastic Zone under 75N



Maximum Normal Stresses

Maximum Shear Stresses



- Strength of single lap joint increases as bondline thickness increases
- CTOA for crack growth in adhesive is independent of bondline thickness
- In DCB fracture test, toughness increases as bondline thickness decreases. This result may be explained in terms of greater confinement of crack tip plastic zone in thinner bondline case
- For thinner bondlines the interfacial stresses between the adhesive and adherend are higher than those for thicker bondlines. It is possible that interfacial strength failure may precede crack extension leading to a lower failure load in joints with thinner bondlines.



Influence of Bondline Thickness and Moisture on Joint Fracture

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Project goals:

 Develop and employ the cohesive zone model approach to fracture to the analysis of adhesive joint failure

• Major achievements/conclusions to date:

- Test procedure to determine cohesive zone model parameters under monotonic loading
- ☑ Transferability of test data between independent crack growth tests
- Test procedure for moisture degradation
- Coupled cohesive zone model for moisture/load interaction

☑ 3D model implementation

• Benefits the aviation industry:

- CZ model approach well established in e.g. microelectronics, civil engineering
- Aid in establishing approach to aviation industry
- Establish approach to long term problems (fatigue, environmental degradation) to reduce testing time



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Experimental Set-up



Crack Growth Resistance

Environmental Degradation





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Moisture Degradation: Experiments





Moisture Degradation: Experiments



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Moisture Degradation: Simulation

As moisture enters the crack process zone, the polymer ligaments loose their strength. In the current model they retain 36% of their strength at full saturation with moisture.



Implementation: Coupled mechanical – transport solution using ABAQUS



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• A Cohesive Zone Model for Fatigue Failure



A Look Forward



- **Benefit to Aviation** *in response to increasing use of adhesive bonding*
 - supports use of more sophisticated computation-based design and analysis tools
 - failure process prediction, including adhesive plasticity
 - CTOA criterion simple to implement

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- VCCT and cohesive zone (cracked & un-cracked) now available in commercial codes
- simulation tools can reduce time to conduct extensive environmental degradation tests
- addressing important issues of bondline thickness
 - quantify phenomena governing why "properties" seemingly depend on bondline thickness
 - definition and use of local failure criteria that are not bondline thickness dependent
- simpler test methods to obtain fracture and constitutive data
 - seeking to define simpler tests and remove necessity to collect data as function of bond thickness



• Future Needs

- account for strain rate dependency and localized failure evolution in constitutive modeling of adhesive – demonstrate transferability to joints of generic configuration
- quantify mixed mode fracture tests via local criterion e.g., CTOA or CZ
- experimentally characterize the interfacial strength between the adhesive and adherends
- fatigue crack growth characterization
- investigate other adherend (namely composite) and adhesive types and failure modes: interfacial (a.k.a. adhesion) and mixed interfacial/cohesive failure + composite failure
- use the developed CTOA and CZ approaches to further investigate the competing nature of interfacial strength and fracture toughness of the adhesive in determining performance of bonded joints
- theoretically study the adhesive properties and bondline thickness for optimal performance of bonded joints